# **SPECIFICATION FOR APPROVAL**

## **COMMODITY:** Infrared Remote-Control Receiver Module

# DEVICE NUMBER: DL-2938LS



CUSTOMER APPROVEDBY	DATE

## Features:

- 1. Photo detector and preamplifier in one package .
- 2. Internal filter for PCM frequency.
- 3. Inner shield, good anti-interference ability.
- 4. High immunity against ambient light.
- 5. Improved shielding against electric field disturbance
- 6. 2.1V or 5.5V supply voltage; low power consumption.
- 7. TTL and CMOS compatibility.
- 8. Suitable transmission code:NEC code,RC5 code.

## Description

- 1. The DL-2938LS is miniaturized infrared receivers for remote control and other applications requiring improved ambient light rejection.
- 2. The separate PIN diode and preamplifier IC are assembled on a single lead frame.
- 3. The epoxy package contains a special IR filter.
- 4. The module has excellent performance even in disturbed ambient light applications and provides protection against uncontrolled output pulses.

#### Applications:

- 1. AV equipment (TV, DVD Player, VCR, Audio, CD player, STB, etc)
- 2. Home appliances (Camera, Computer Air Conditioner, Fan, light, etc)
- 3. Infrared remote control Toys.

Package dimensions:



Part No.	Chip Material	Lens Color	Source Color
DL-2938LS	Silicon	Black	Infrared Receiver

NOTES:

1.All dimensions are in millimeters (inches).

- 2.Tolerance is ±0.30mm (0.012") unless otherwise specified.
- 3.Specifications are subject to change without notice.

## ♦ Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Ratings	Unit
Supply Voltage	Vcc	2.4-6.5	V
Operating Temperature	Topr	-25~ +65	°C
Storage Temperature	Tstg	-40 ~ +85	°C
Soldering Temperature *1	Tsol	260	°C

## ◆ Electrical Optical Characteristics at Ta=25 ℃

Parameter	Symbol	Ratings			Unit	Condition	
	Symbol	Min.	Тур.	Max.		condition	
Supply Voltage	Vs	2.7	-	6	v		
Supply Current	lcc			0.6	mA	No signal input	
Reception Distance	Lo	16		_	m	At the ray axis*1	
	L <sub>45</sub>	8					
B.P.F Center Frequency	fo		38	_	KHz		
Peak Wavelength	λр		940	_	nm		
Half Angle	θ		45		deg	At the ray axis *1	
High Level Pulse Width	Т <sub>н</sub>	400		800	μS		
Low Level Pulse Width	Τι	400		800	μS	At the ray axis *2	
High Level Output Voltage	V <sub>H</sub>	Vcc-0.3		_	v		
Low Level Output Voltage	VL			0.3	v		

Notes:

1. The ray receiving surface at a vertex and relation to the ray axis in the range of  $\theta$ =0° and  $\theta$ =45°.

2. A range from 30cm to the arrival distance. Average value of 50 pulses.

## Block Diagram



#### 2Test Method

#### A.Standard Transmitter





#### **B.Detection Length Test**



#### C.Pulse Width Test



#### D.U.T Output Pulse





#### • Application Circuit



# Typical Electrical - Optical Characteristics Curves (25°C Ambient Temperature Unless Otherwise Noted)



Fig.3 Frequency Dependence of Responsivity





Fig.2 Relative Transmission Distance Vs. Direction





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Classification	Test Item	Reference Standard	Test Conditions	Result
	Operation Life	MIL-STD-750:1026	Connect with a power If=20mA	
		MIL-STD-883:1005	Ta=Under room temperature	0/20
		JIS-C-7021 :B-1	Test time=1,000hrs	
	High Temperature	MIL-STD-202:103B	Ta=+65℃±5℃	
	High Humidity	JIS-C-7021 :B-11	RH=90%-95%	0/20
	Storage		Test time=240hrs	
Endurance Test	High Temperature	MIL-STD-883:1008	Нірh Та=85℃+5℃	
	Storage	JIS-C-7021 :B-10	Test time=1.000hrs 0/20	0/20
	Low Temperature	JIS-C-7021 :B-12	Low Ta=-35 °C±5 °C	0/20
	Storage		Test time=1,000hrs	
	Temperature	MIL-STD-202:107D	-35℃ ~ +25℃ ~ +85℃ ~ +25℃	
	Cycling	MIL-STD-750:1051	60min 20min 60min 20min	0/20
		MIL-STD-883:1010	Test Time=5cycle	
		JIS-C-7021 :A-4		
Environmental	Thermal Shock	MIL-STD-202:107D	35℃±5℃ ~+85℃±5℃	0/20
Test		MIL-STD-750:1051	20min 20min	0/20
		MIL-STD-883:1011	Test Time=10cycle	
	Solder Resistance	MIL-STD-202:201A	Preheating:	
		MIL-STD-750:2031	140 $^\circ$ C −160 $^\circ$ C , within 2 minutes.	0/20
		JIS-C-7021 :A-1	Operation heating: 235℃	
			(Max.), within 10seconds (Max.)	

## • Judgment criteria of failure for the reliability

Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Forward voltage	VF (V)	IF=20mA	Over Ux1.2
Reverse current	IR(uA)	VR=5V	Over Ux2
Luminous intensity	lv (mcd)	IF=20mA	Below SX0.5

#### Notes:

- 1. U means the upper limit of specified characteristics. S means initial value.
- 2. Measurement shall be taken between 2 hours and after the test pieces have been returned to normal ambient conditions after completion of each test.

## • Soldering:

1. Manual of Soldering

The temperature of the iron tip should not be higher than 300  $^{\circ}$ C (572  $^{\circ}$ F) and Soldering within 3 seconds per solder-land is to be observed.

2. Reflow Soldering

Preheating:  $140^{\circ}$ C~ $160^{\circ}$ C  $\pm 5^{\circ}$ C, within 2 minutes.

Operation heating: 235  $^{\circ}$ C (Max.) within 10 seconds (Max)

Gradual Cooling (Avoid quenching).



3. DIP soldering (Wave Soldering):

Preheating:  $120^{\circ}$ C~150°C, within 120~180 sec.

Operation heating:  $245^{\circ}C \pm 5^{\circ}C$  within 5 sec.260 $^{\circ}C$  (Max)

Gradual Cooling (Avoid quenching).



## • Handling :

Care must be taken not to cause to the epoxy resin portion of LEDs while it is exposed to high temperature. Care must be taken not rub the epoxy resin portion of LEDs with hard or sharp article such as the sand blast and the metal hook.

## • Notes for designing:

Care must be taken to provide the current limiting resistor in the circuit so as to drive the LEDs within the rated figures. Also, caution should be taken not to overload LEDs with instantaneous voltage at the turning ON and OFF of the circuit.

When using the pulse drive care must be taken to keep the average current within the rated figures. Also, the circuit should be designed so as be subjected to reverse voltage when turning off the LEDs.

#### • Storage:

In order to avoid the absorption of moisture, it is recommended to solder LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

- 1) Temperature : 5  $^\circ C$  -30  $^\circ C$  (41  $^\circ F$  ), Humidity : RH 60  $^{\%}$  Max.
- 2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:
  - a) Completed within 24 hours.
  - b) Stored at less than 30% RH.
- 3) Devices require baking before mounting, if (2) a or (2) b is not met.
- 4) If baking is required, devices must be baked under below conditions: 12 hours at  $60^{\circ}C\pm3^{\circ}C$ .